

SPECIFICATION
COMMERCIALY AVAILABLE

ITEM: CERAMIC BAND PASS
 PART NUMBER:CF-27005009
 RoHS

ISSUED	CHECKED	CHECKED	CHECKED	APPROVED
6/26/09 ^(kn)				
5/16/13 ^(kn)			06/03/2013 GL	06/03/2013 TFG

FILTRONETICS Inc

1. APPLICATION

THIS SPECIFICATION APPLIES TO BAND PASS FILTER, USING DIELECTRIC RESONATORS.

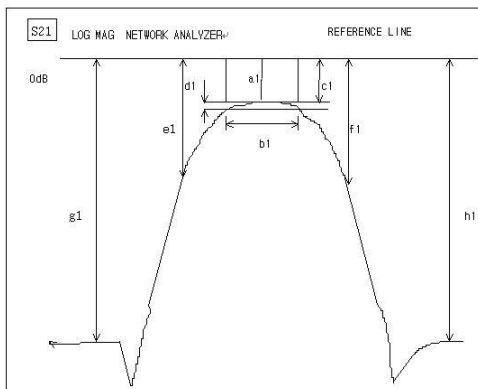
2. PART NUMBER

PART NO	CF-27005009
PACKAGING	PLASTIC TRAY

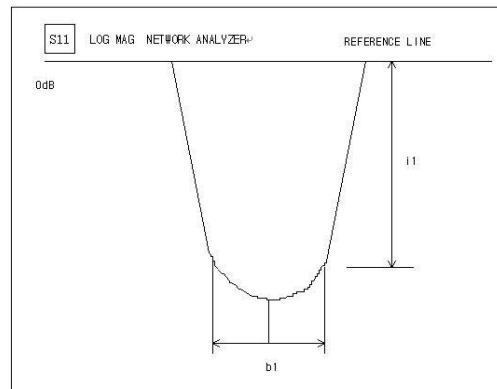
3. SPECIFICATIONS

NO	ITEMS	Ref.	SPECIFICATION
1	Center Frequency (Fo)	-	2700 MHz
2	Pass Band Width(=PB)	-	2450~2950MHz
3	Insertion Loss at Fo	-	3.2 Db Max
4	2.0dB BAND WIDTH	-	500MHz Min
5	Attenuation [Absolute Value]	At 1500~2300MHz	50dB Min
		At 3100MHz	40dB Min
		At 3200~4000MHz	50dB Min
6	Return Loss IN PB	-	12dB Min
7	Group Delay Variation IN PB	-	30nsec Max
8	Impedance	-	50Ω
9	Maximum Input Power	-	1 W (+30dBm)
10	Operating Temperature Range	-	-30 - +70°C

S21 LOG MAG NETWORK ANALYZER



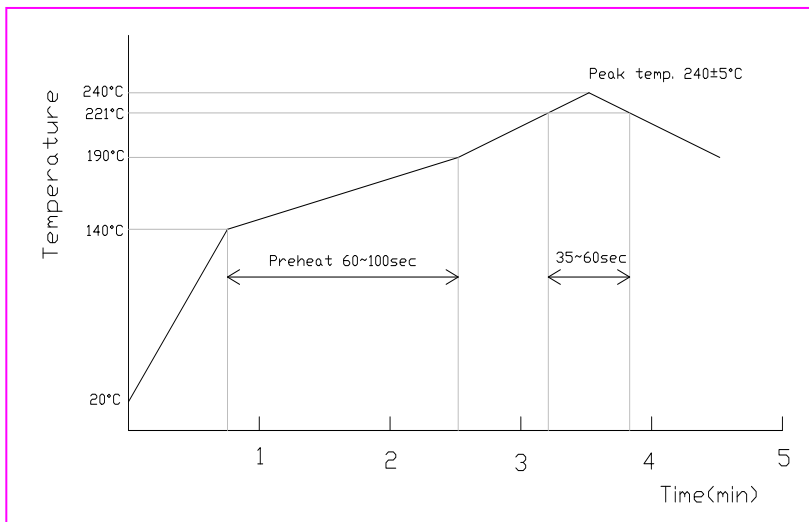
S11 LOG MAG NETWORK ANALYZER



6. DEFINITIONS

TERMS	DESCRIPTION	SPECIFICATION
Center Frequency	The midpoint of through band pass filter pass band, normally expressed as the arithmetic mean of the -3dB point. Also called Fo.	3. SPECIFICATION
Pass Band Width	The width of the pass band of a filter referenced to the minimum insertion loss point in the pass band. The pass band of a filter is stated as -1.0dB bandwidth.	
Insertion Loss	The loss of the filter, in dB, measured at center frequency relative to a through line (0 dB).	
Attenuation	Reduction of RF power through a filter measured in dB, at desired band and referenced to 0 dB. (Filter to be removed from circuit)	
Pass Band Ripple	Variations in loss in the pass band of the filter, superimposed upon the fundamental shape of the pass band.	
V.S.W.R in Pass Band	The ratio of the maximum value of a standing wave to its minimum value, related to the return loss in pass band.	
Date Code	Each date code shall be from a single lot	
Lot	One Batch of parts processed in a single manufacturing run. A single lot shall have no more than one firing, plating, soldering, or other batch processing.	
Cleanliness	Parts shall be clean. They shall be free from smudges, loose solder, solder spatter, metal chips or mold release agents. No burrs. Particles or any foreign material over 0.2 mm which might detract from the intended operation, function or appearance of the part.	

7. REFLOW SOLDERING STANDARD CONDITIONS FOR RoHS



- Measuring point of temperature in-out terminals of the device.
- Reflow Soldering
- Both convection and infrared rays
- Hot air
- Hot plates
- Solder Cream: Sn96.5/Ag3.5